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(12) **United States Design Patent**
Buck et al.

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(54) **CONTACT WAFER**

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(73) Assignee: **SAMTEC, INC.**, New Albany, IN (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/725,389**

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Related U.S. Application Data

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/154**

(58) **Field of Classification Search**
USPC D13/154, 147, 123, 133, 146, 184, 199
CPC .. H01R 13/6477; H01R 12/724; H01R 13/41; H01R 13/514; H01R 13/6315; H01R 13/646; H03H 7/38
See application file for complete search history.

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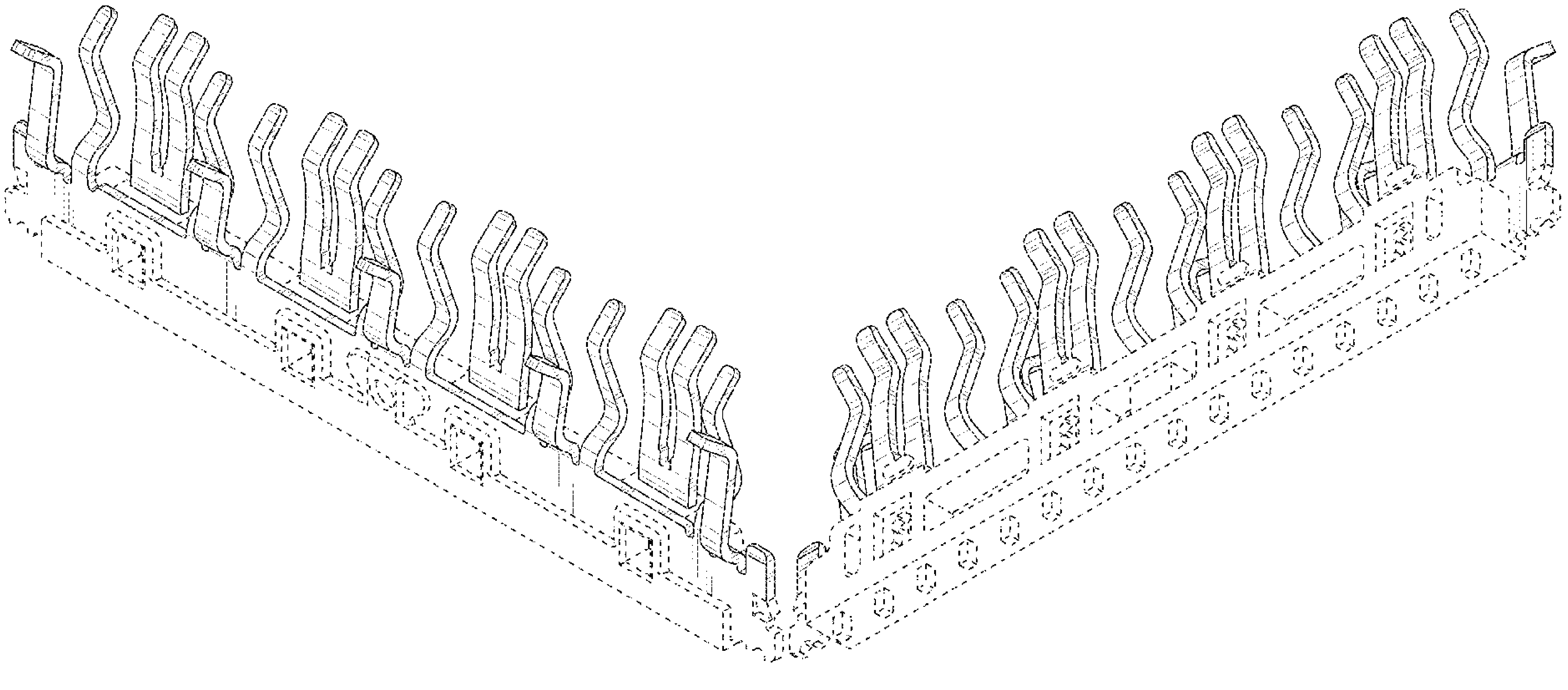
(57) **CLAIM**

The ornamental design for contact wafer, as shown and described.

DESCRIPTION

FIG. **1** is a top, front, and right side perspective view of a contact wafer showing our new design;
FIG. **2** is a bottom, back, and left side perspective view thereof;
FIG. **3** is a front view thereof;
FIG. **4** is a back view thereof;
FIG. **5** is a left thereof;
FIG. **6** is a right view thereof;
FIG. **7** is a top view thereof; and,
FIG. **8** is a bottom view thereof.
The broken lines in the drawing views are included to show portions of the contact wafer that form no part of the claimed design.

1 Claim, 8 Drawing Sheets



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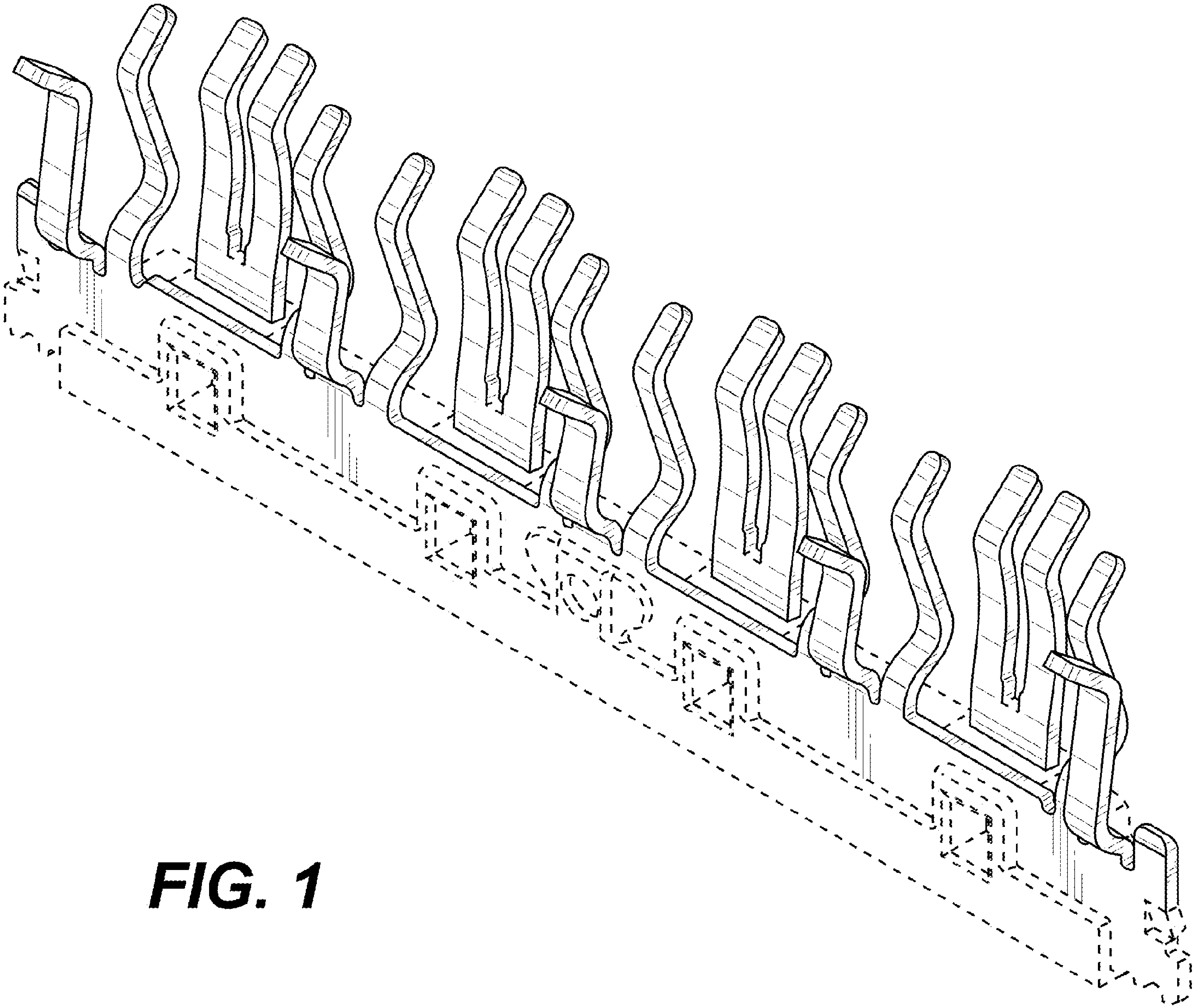

FIG. 1

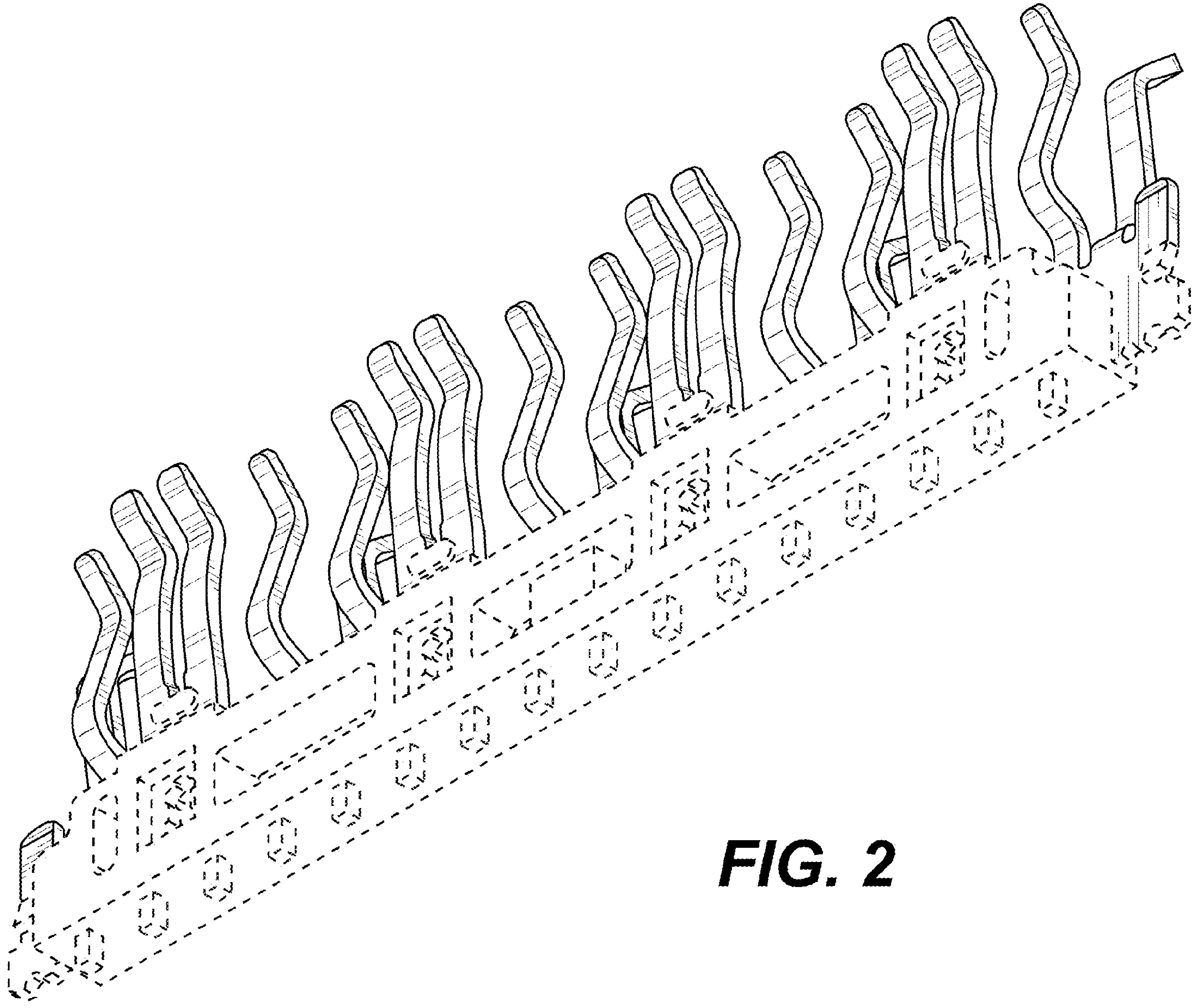

FIG. 2

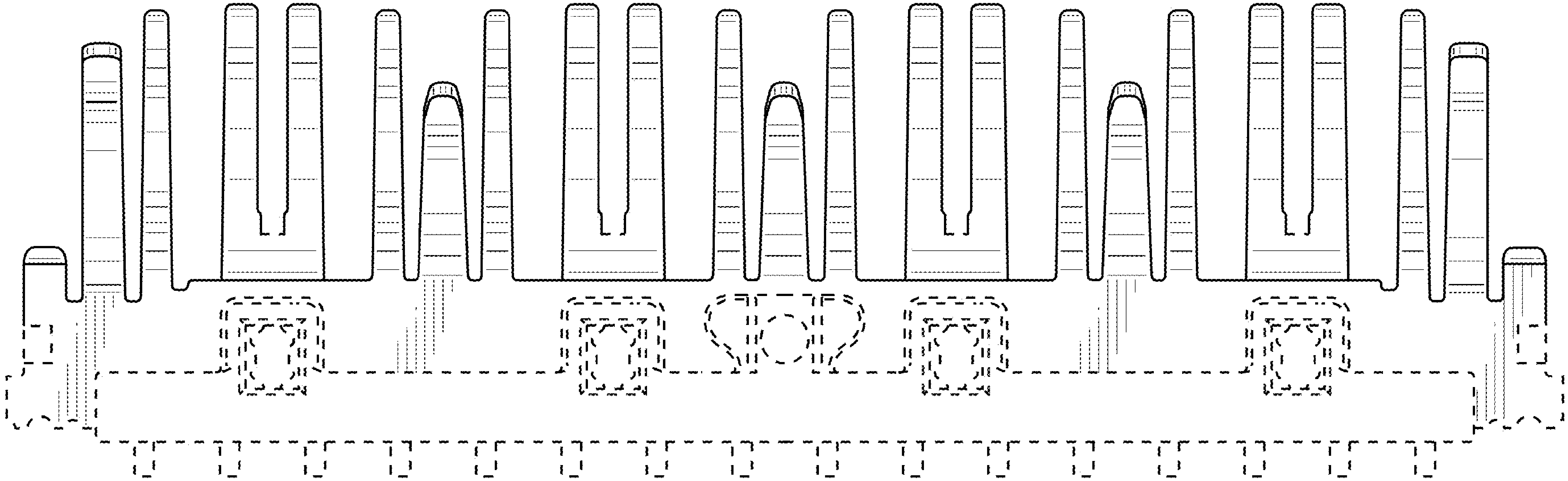

FIG. 3

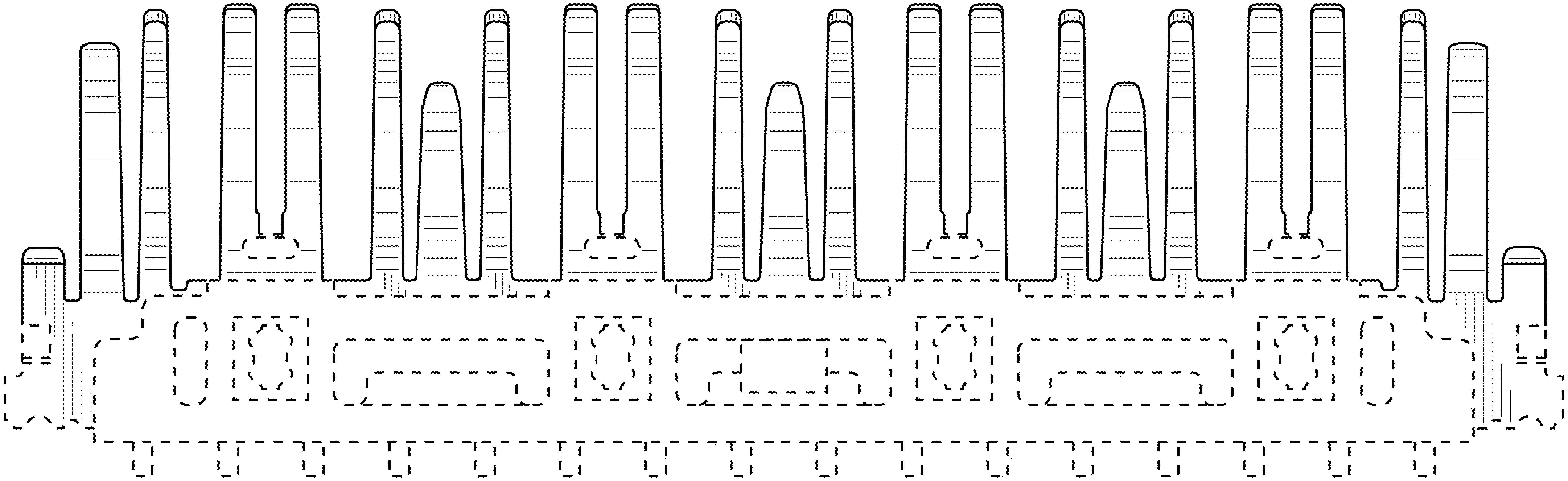

FIG. 4

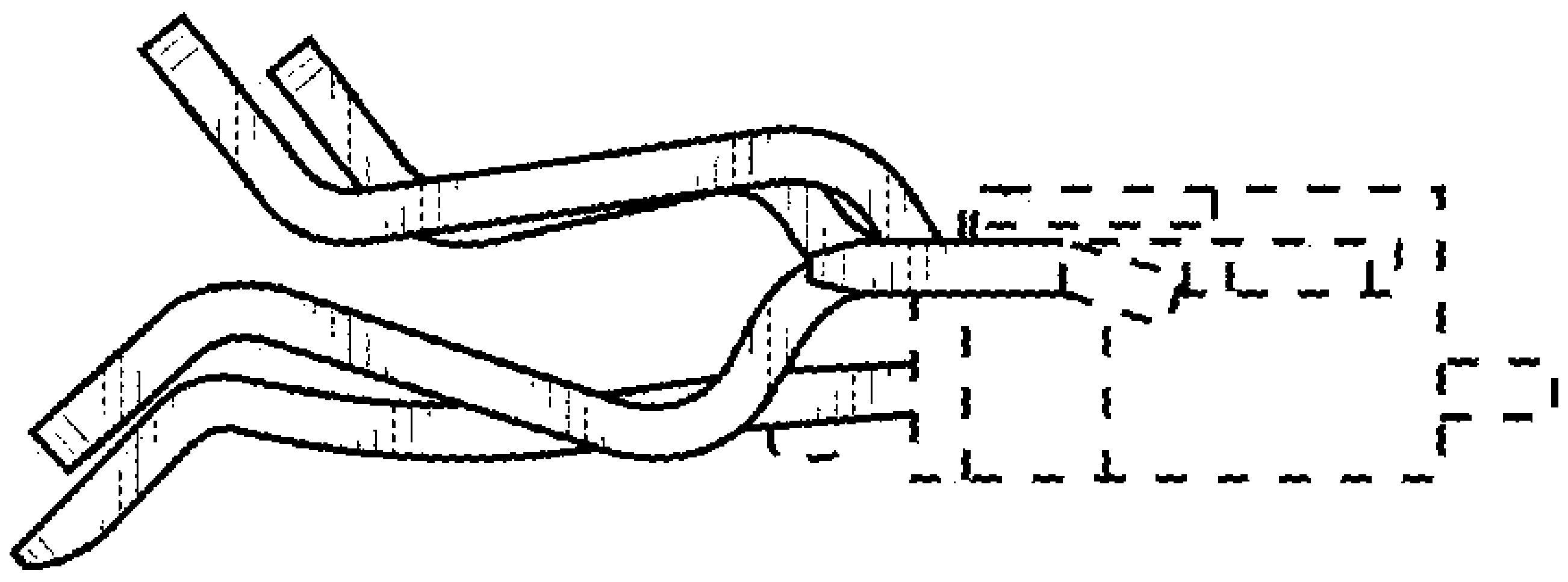

FIG. 5

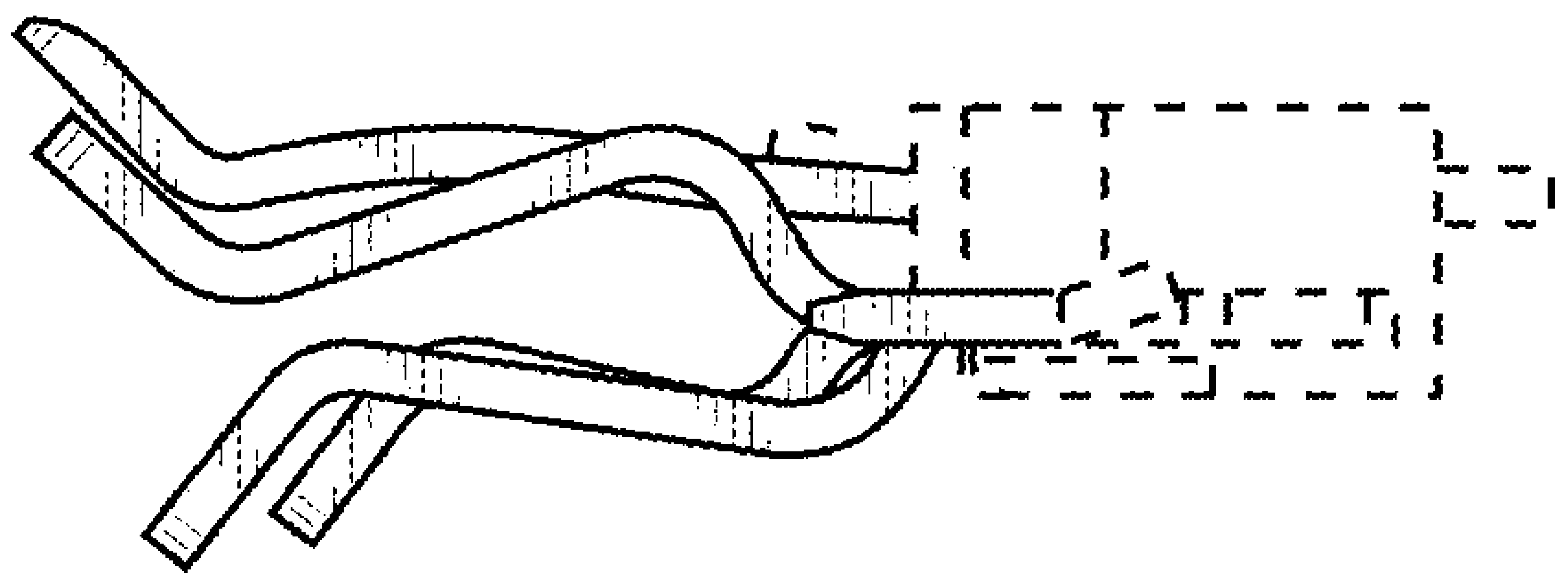

FIG. 6

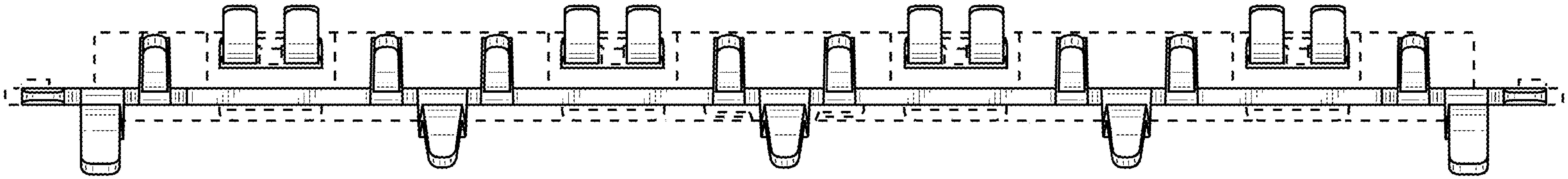

FIG. 7

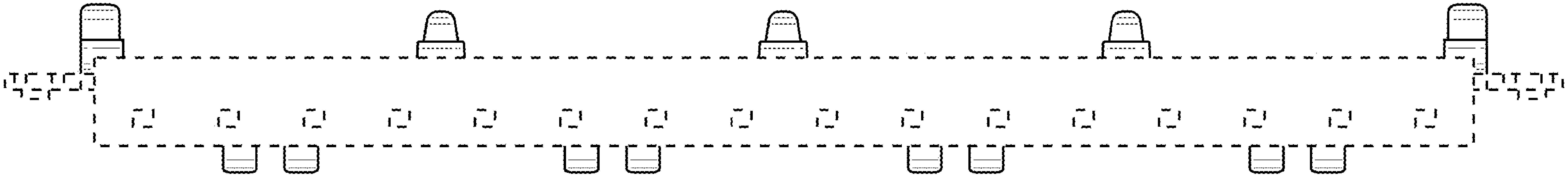

FIG. 8